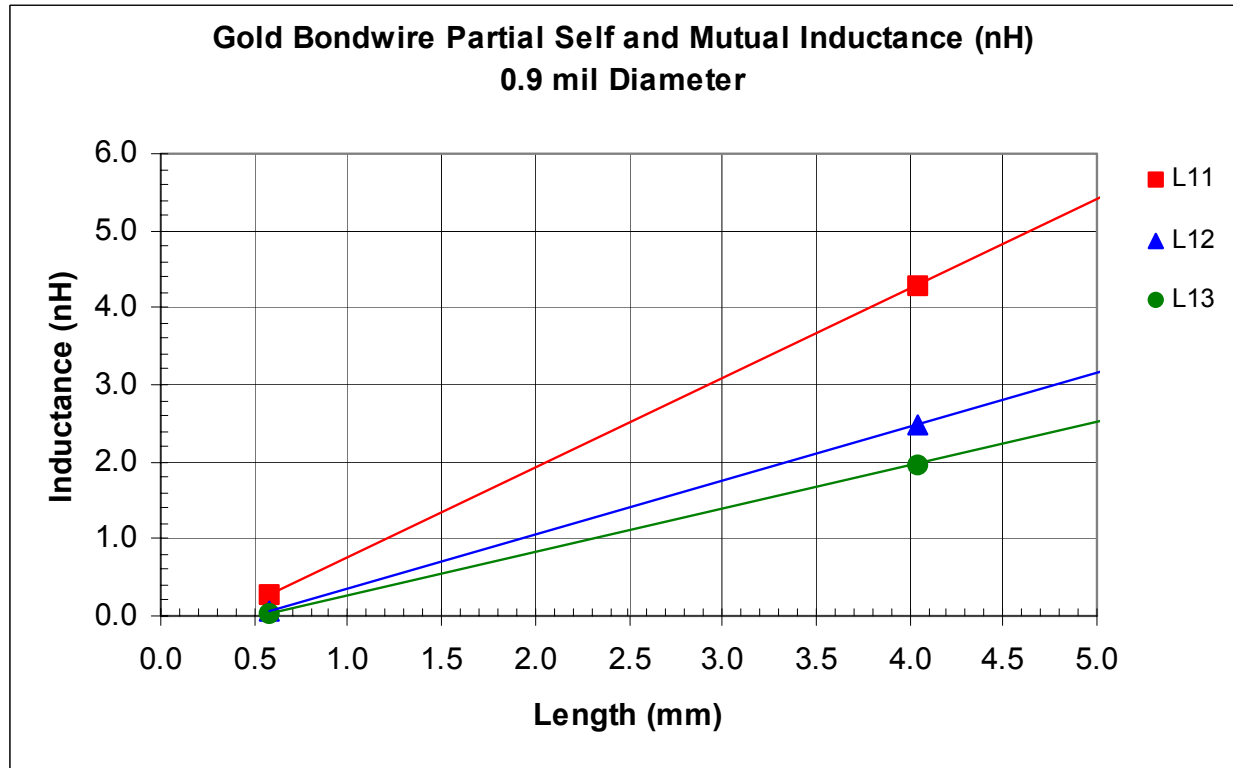


3D Bondwire Electrical Modeling Results

0.9 mil Diameter



$L11 = 1.1633x - 0.4141$
$L12 = 0.6983x - 0.3385$
$L13 = 0.5603x - 0.2914$

Bondwire Diameter = 0.9 mil

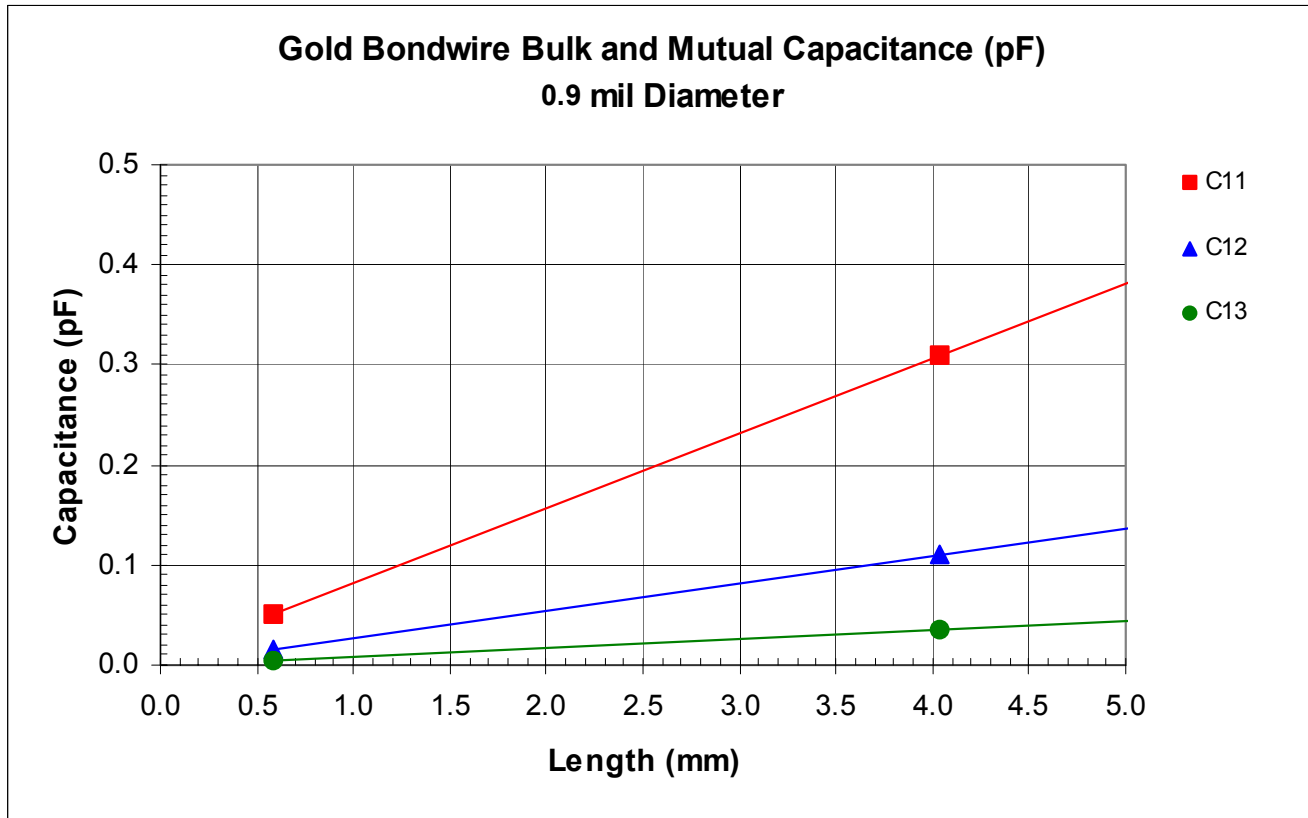
Die Pad Pitch = 75 μ m

Bond Finger Pitch = 160 μ m

Mold Compound Dielectric Constant = 3.9

3D Bondwire Electrical Modeling Results

0.9 mil Diameter



Bondwire Diameter = 0.9 mil

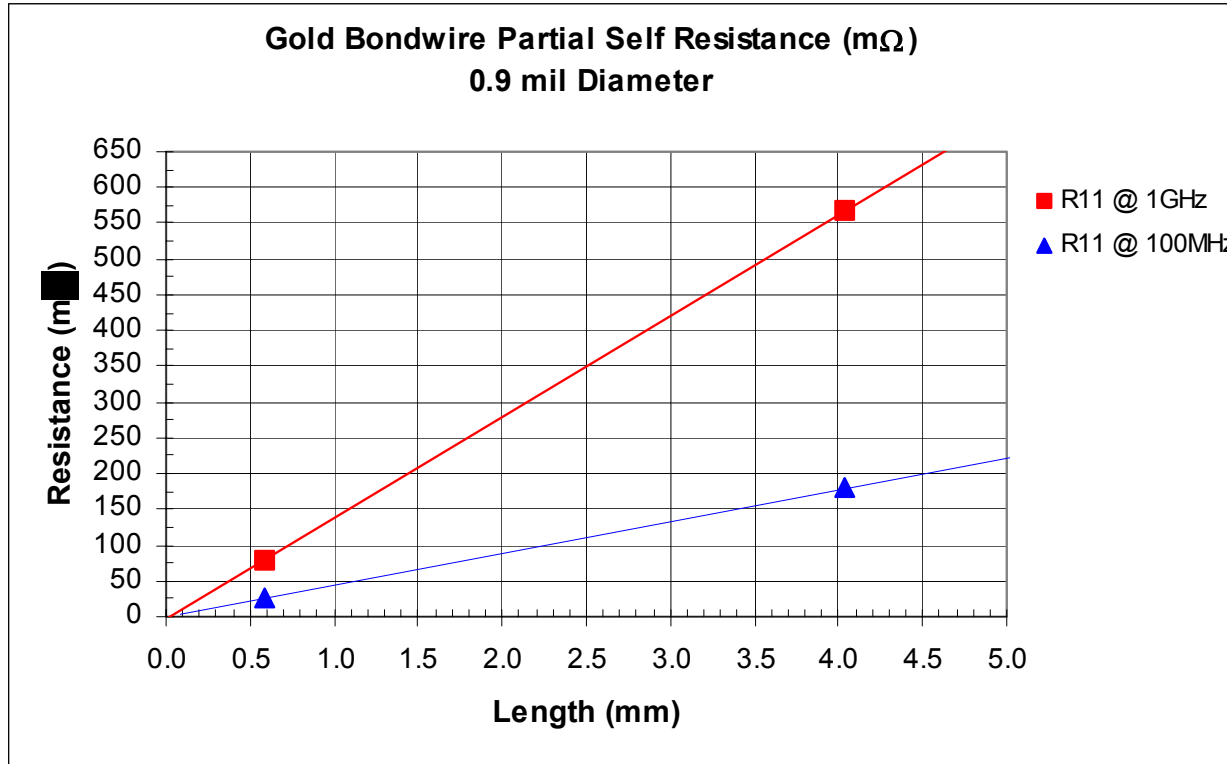
Die Pad Pitch = 75 μ m

Bond Finger Pitch = 160 μ m

Mold Compound Dielectric Constant = 3.9

3D Bondwire Electrical Modeling Results

0.9 mil Diameter



$R_{11} @ 100\text{MHz} = 44.599x - 0.5229$
$R_{11} @ 1\text{GHz} = 141.04x - 1.6535$

Bondwire Diameter = 0.9 mil

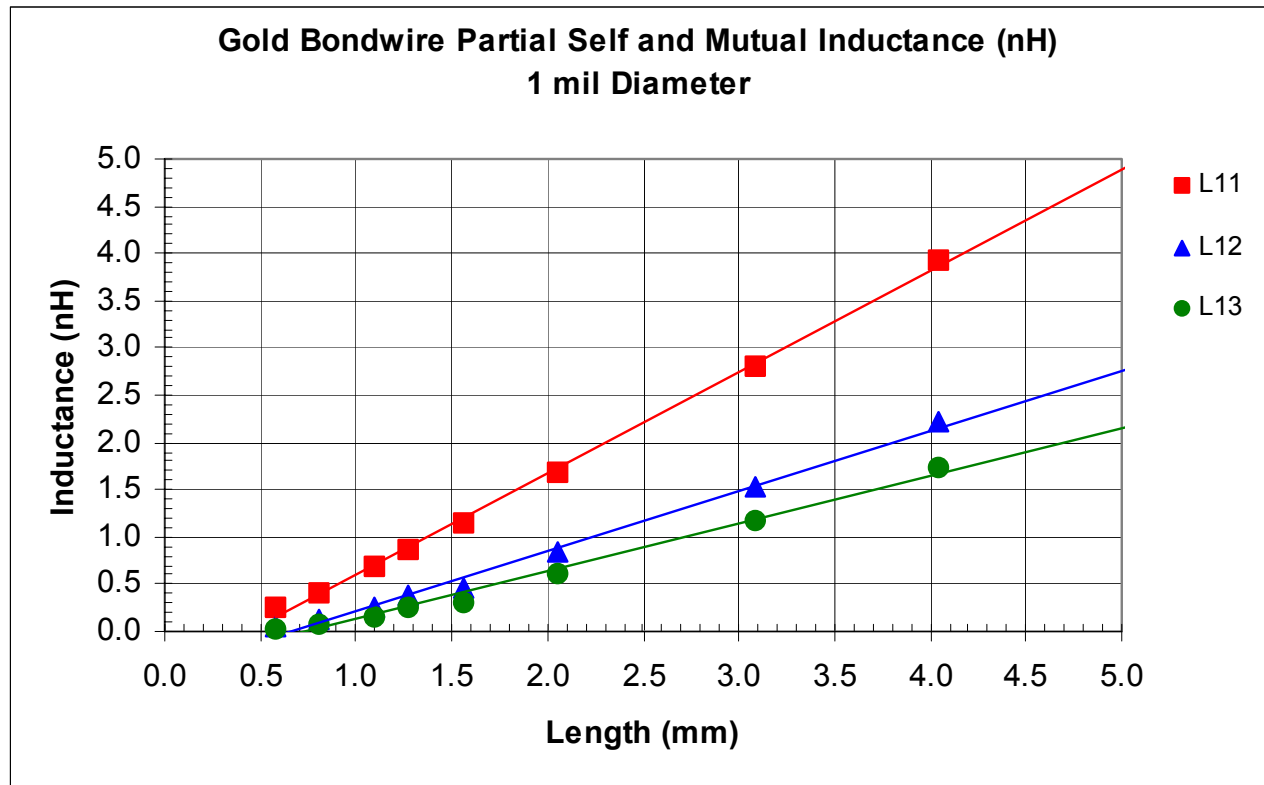
Die Pad Pitch = 75 μm

Bond Finger Pitch = 160 μm

Mold Compound Dielectric Constant = 3.9

3D Bondwire Electrical Modeling Results

1 mil Diameter



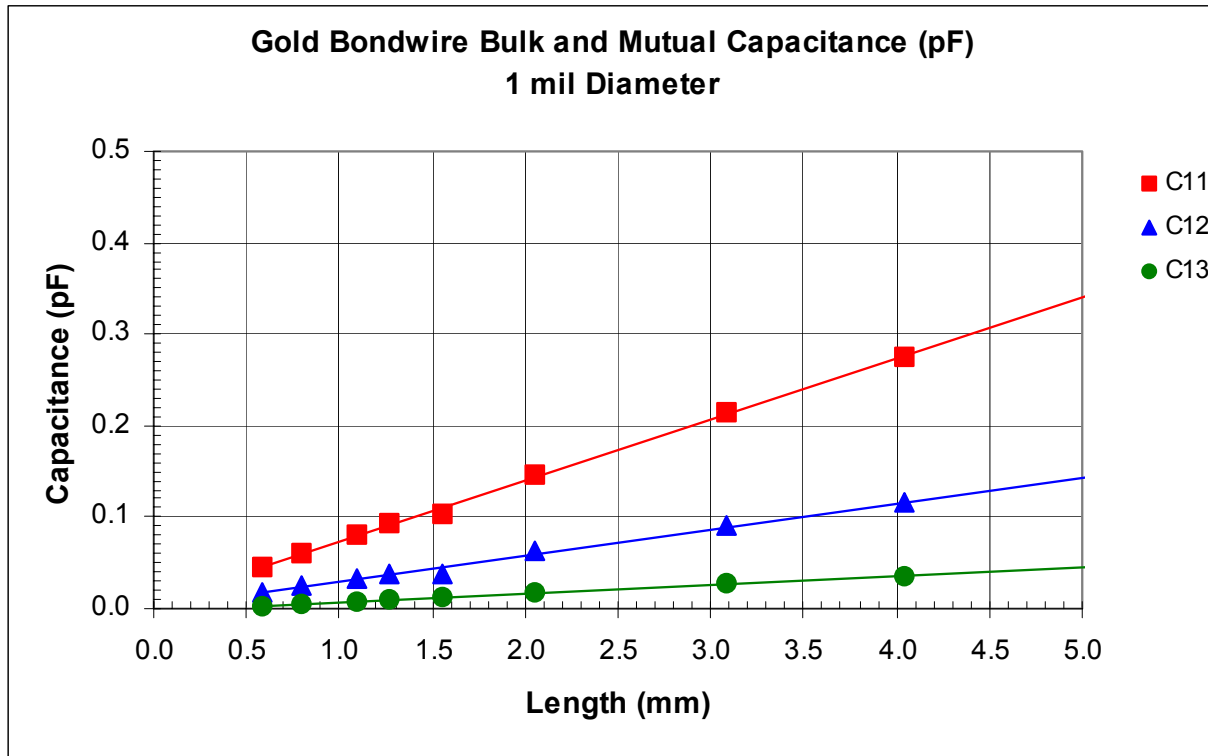
Bondwire Diameter = 1 mil

Die Pad Pitch = 75 um

Bond Finger Pitch = 160 um

Mold Compound Dielectric Constant = 3.9

3D Bondwire Electrical Modeling Results 1 mil Diameter



$C11 = 0.0783x + 0.0064$
$C12 = 0.0287x + 0.0004$
$C13 = 0.0094x - 0.0017$

Bondwire Diameter = 1 mil

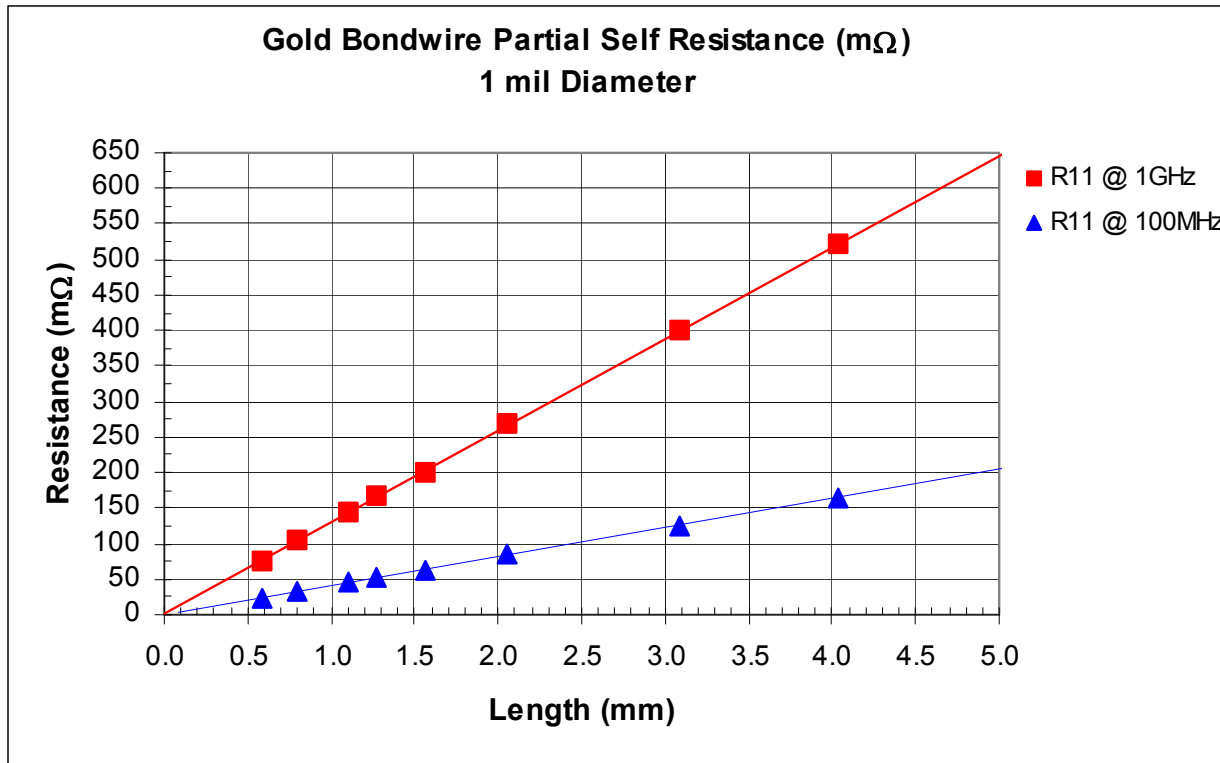
Die Pad Pitch = 75 μ m

Bond Finger Pitch = 160 μ m

Mold Compound Dielectric Constant = 3.9

3D Bondwire Electrical Modeling Results

1 mil Diameter



$$R_{11} @ 100\text{MHz} = 40.699x + 0.6372$$
$$R_{11} @ 1\text{GHz} = 128.7x + 2.0149$$

Bondwire Diameter = 1 mil

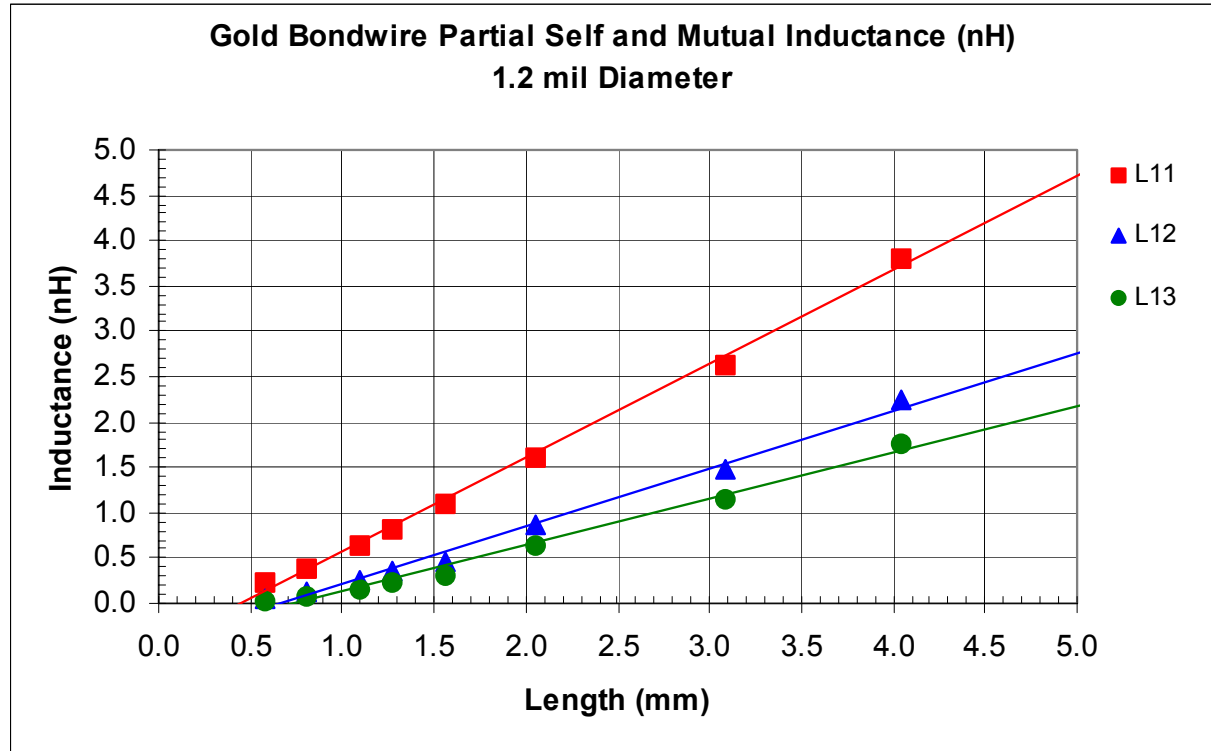
Die Pad Pitch = 75 μm

Bond Finger Pitch = 160 μm

Mold Compound Dielectric Constant = 3.9

3D Bondwire Electrical Modeling Results

1.2 mil Diameter



Bondwire Diameter = 1.2 mil

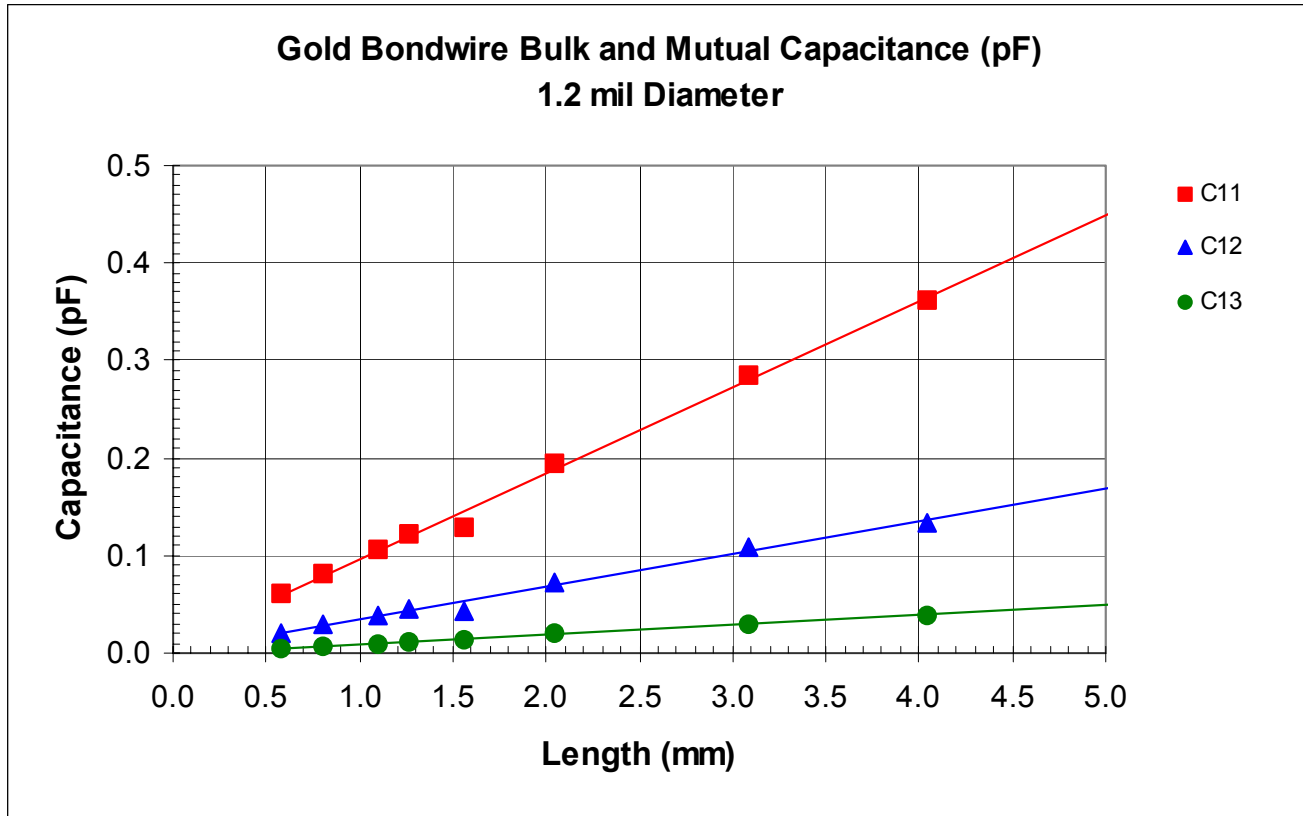
Die Pad Pitch = 75 um

Bond Finger Pitch = 160 um

Mold Compound Dielectric Constant = 3.9

3D Bondwire Electrical Modeling Results

1.2 mil Diameter



Bondwire Diameter = 1.2 mil

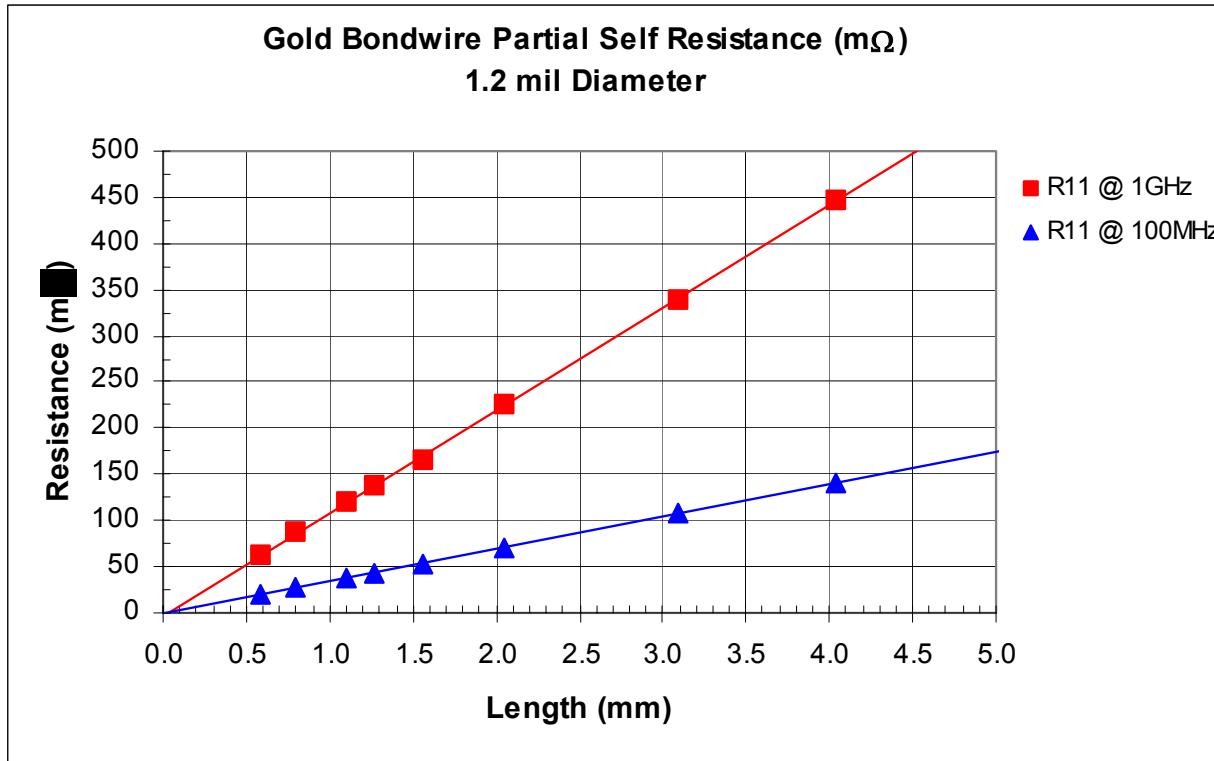
Die Pad Pitch = 75 μ m

Bond Finger Pitch = 160 μ m

Mold Compound Dielectric Constant = 3.9

3D Bondwire Electrical Modeling Results

1.2 mil Diameter



$R_{11} @ 100\text{MHz} = 35.153x - 1.004$
$R_{11} @ 1\text{GHz} = 111.16x - 3.1749$

Bondwire Diameter = 1.2 mil

Die Pad Pitch = 75 μm

Bond Finger Pitch = 160 μm

Mold Compound Dielectric Constant = 3.9